

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT5461056

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JAEHOON HAN	03/29/2019
SANGHYEON KIM	03/29/2019
HYUNSU JU	03/29/2019
JIN-DONG SONG	03/29/2019
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16376672
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SIGNATURE:	/James J. Merrick/
DATE SIGNED:	04/05/2019
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 2	

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ASSIGNMENT

WHEREAS WE, **HAN, Jachoon** of 5, Hwarang-ro 14-gil, Seongbuk-gu, Seoul, 02792, Republic of Korea; **KIM, Sanghyeon** of 5, Hwarang-ro 14-gil, Seongbuk-gu, Seoul, 02792, Republic of Korea; **JU, Hyunsu** of 5, Hwarang-ro 14-gil, Seongbuk-gu, Seoul, 02792, Republic of Korea and **SONG, Jin-Dong** of 5, Hwarang-ro 14-gil, Seongbuk-gu, Seoul, 02792, Republic of Korea (hereinafter collectively referred to as the “**ASSIGNORS**”), have invented certain new and useful improvements in:

THE METHOD FOR OPTICAL INTERCONNECTION BETWEEN SEMICONDUCTOR CHIPS USING MID-INFRARED

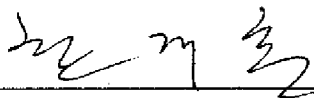
(hereinafter referred to as the “**INVENTION**”) which claims priority to Korean Application No. 10-2018-0039807, filed on 5 April, 2018 (hereinafter collectively referred to as the “**APPLICATIONS**”);

AND WHEREAS, **KOREA INSTITUTE OF SCIENCE AND TECHNOLOGY** (hereinafter referred to as “**ASSIGNEE**”), a corporation organized and existing under the laws of the Country of **Republic of Korea**, having a place of business at **5, Hwarang-ro 14-gil, Seongbuk-gu, Seoul, 02792, Republic of Korea**, is desirous of acquiring an interest in any and all countries, in and to the **INVENTION**, the **APPLICATIONS**, and any and all Patents to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for good and valuable consideration, the receipt of which is hereby acknowledged, we, the **ASSIGNORS**, have assigned and transferred, and hereby assign and transfer unto **ASSIGNEE**, the entire right, title and interest in and to the **INVENTION**, the **APPLICATIONS**, and any and all Patents that may be issued therefrom, in any and all countries, including any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to **ASSIGNEE**; and we do hereby agree that we will execute all papers necessary in connection with any and all patent applications when called upon to do so by **ASSIGNEE**, its successors or assigns, and that we will, at the cost and expense of **ASSIGNEE**, fully assist and cooperate in all matters in connection with any and all patent applications and Patents issuing thereon.

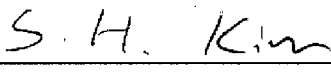
The undersigned declare that all statements made herein of his own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the APPLICATIONS or any Patents issuing thereon.

Date: 2019/3/29



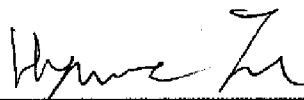
HAN, Jaehoon

Date: 2019/3/29



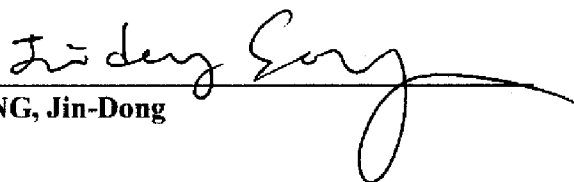
KIM, Sanghyeon

Date: 2019/03/29



JU, Hyunsu

Date: 2019/3/29



SONG, Jin-Dong